

# **Prospettive sulle alimentazioni per il tracciatore di CMS a HL-LHC**

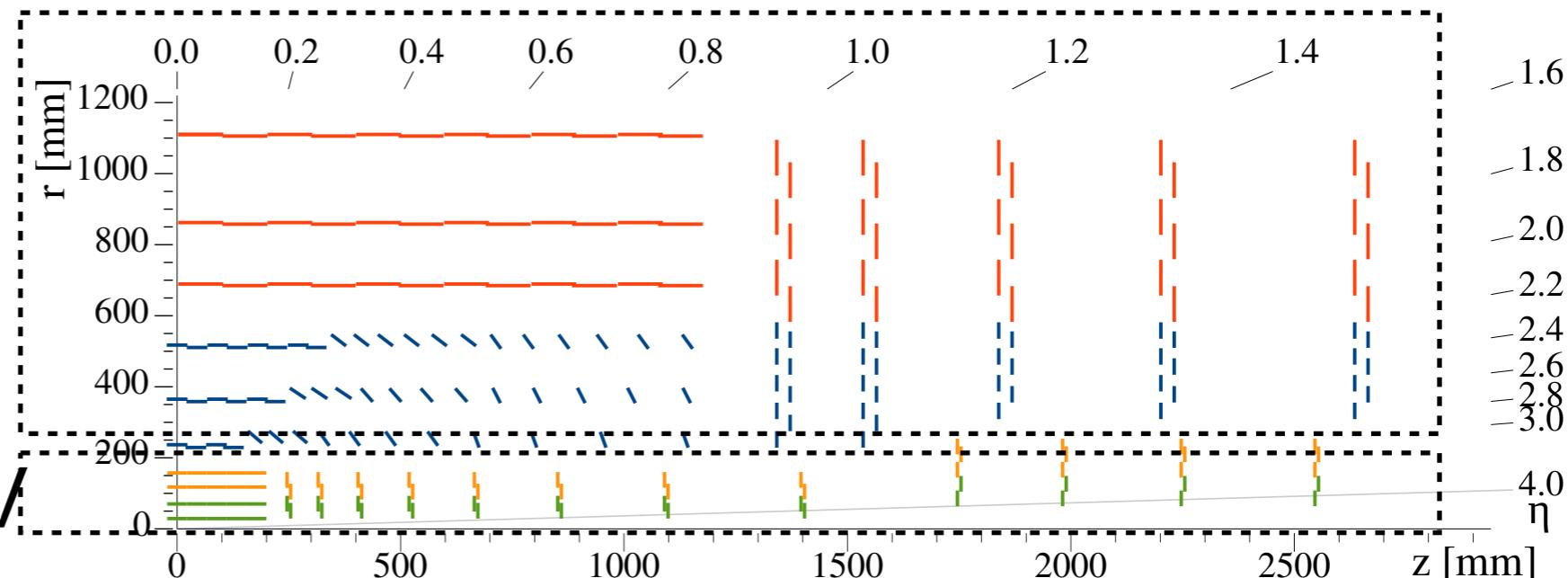
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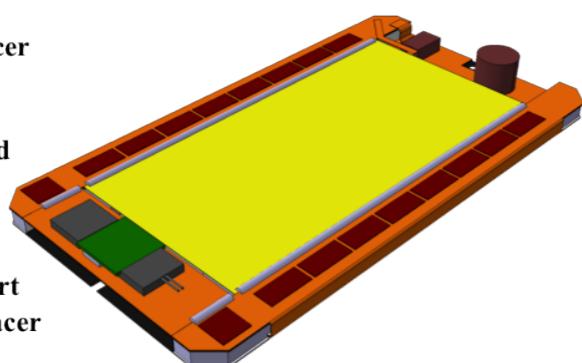
# Il tracciatore per HL-LHC

$\sim 100 \text{ kW} @ \sim 11\text{V}$

$\sim 40 \text{ kW} @ 1.2\text{V} + 0.8 \text{ V}$



1. PS-s silicon sensor
2. PS-p silicon sensor
3. MPAs
4. Al-CF sensor spacer
5. CFRP base plate
6. FE Hybrid
7. Opto-Link Hybrid
8. Power Hybrid
9. SSA
10. CIC
11. Hybrid CF support
12. Al-CF Hybrid spacer



$2.5 \text{ V}, 1.00 \text{ V}, 1.25 \text{ V}$

## Outer Tracker:

$\sim 8200 \text{ 2S modules}$

$\sim 5300 \text{ PS modules}$

$\sim 6 \text{ W per PS module}$

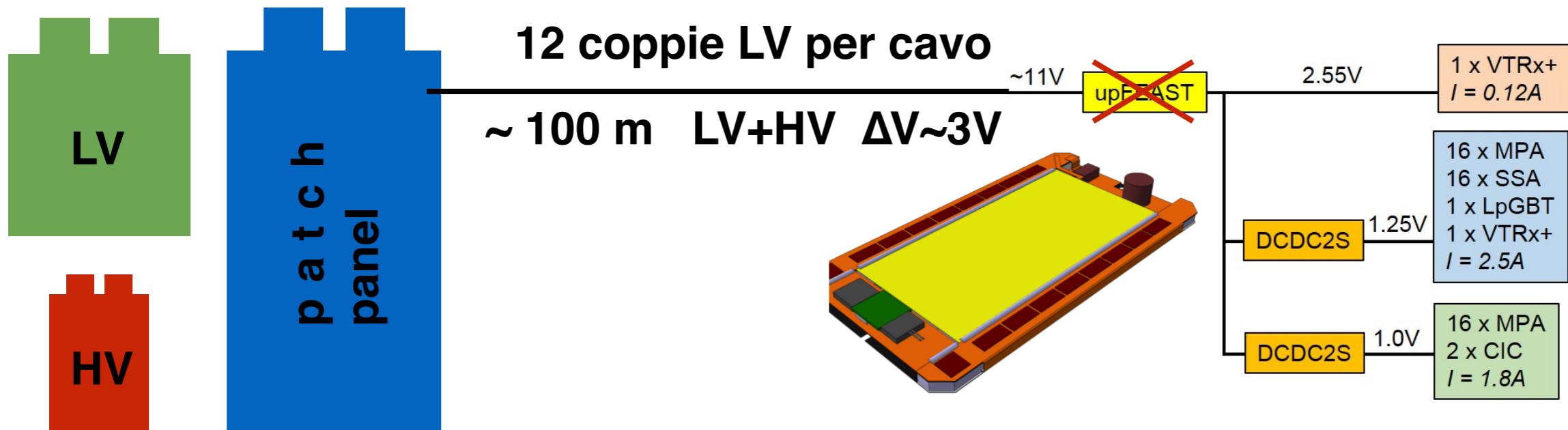
$\sim 3 \text{ W per 2S module}$

## Pixel:

$\sim 4000 \text{ modules}$

$\sim 13\,000 \text{ R/O chips}$   
(RD53)

# Alimentazione moduli OT

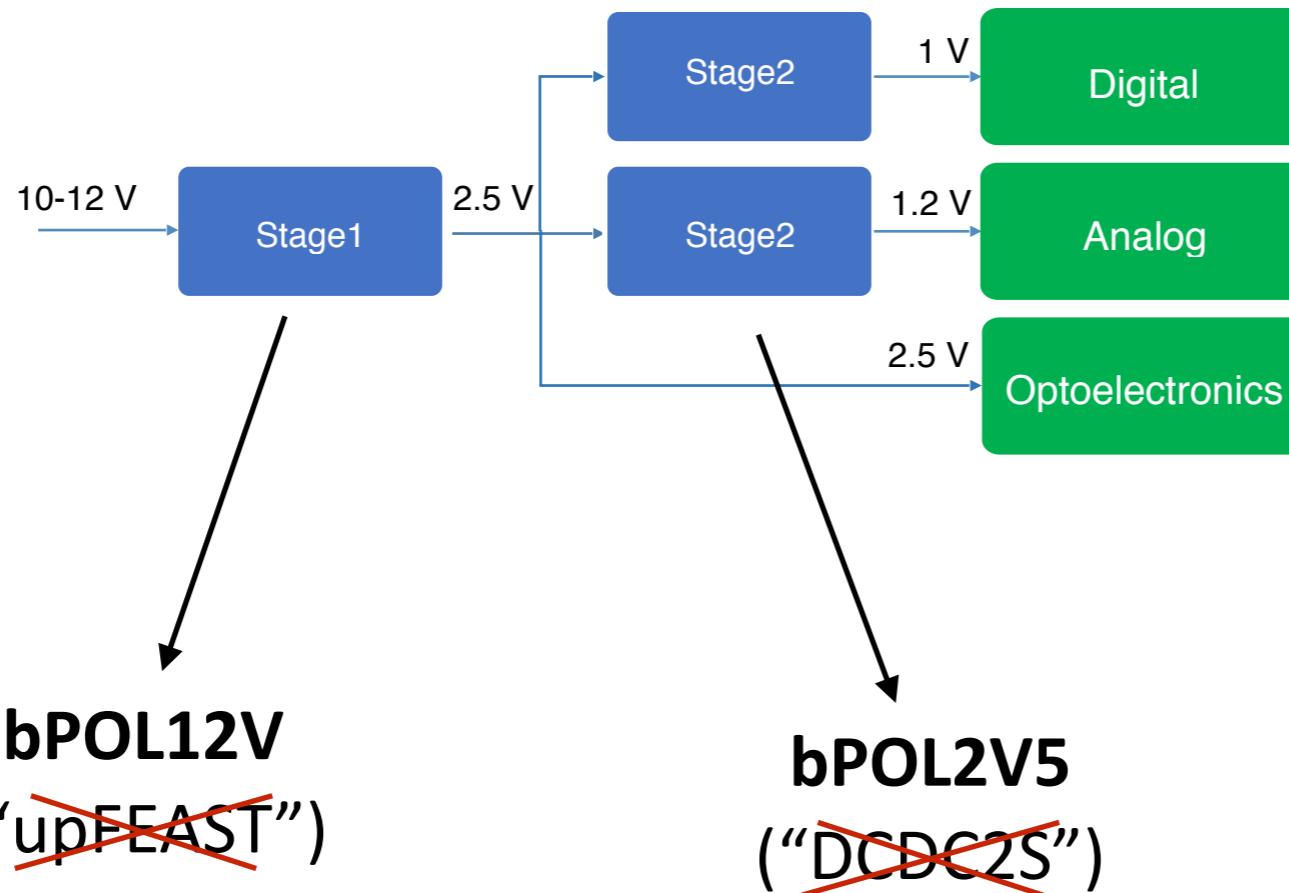


- No power → no communication to module
- ~ 13 000 fili LV da back-end a detector da gestire
- Alimentazione di DC/DC (carico non Ohmico)
- ! Gestione transienti (power-ON, power-OFF etc.) → specifiche del DC/DC converter
- Efficienza dopo irraggiamento
- Interplay LV ↔ HV

? Ubicazione ? (Area ostile o USC ?)

? Sezione dei cavi ?

? Current compensation ?



Input voltage	6.0 V ÷ 12 V
Output voltage	0.6 V ÷ 5 V
Output current	≤ 4 A
Switching frequency	1.5 ÷ 3 MHz
Inductor value	200 ÷ 500 nH

Input voltage	2.0 V ÷ 2.5 V
Output voltage	0.6 V ÷ 1.5 V
Output current	≤ 3 A
Switching frequency	≥ 4 MHz
Inductor value	< 120 nH

Radiation environment without safety factors

TID: 100 Mrad

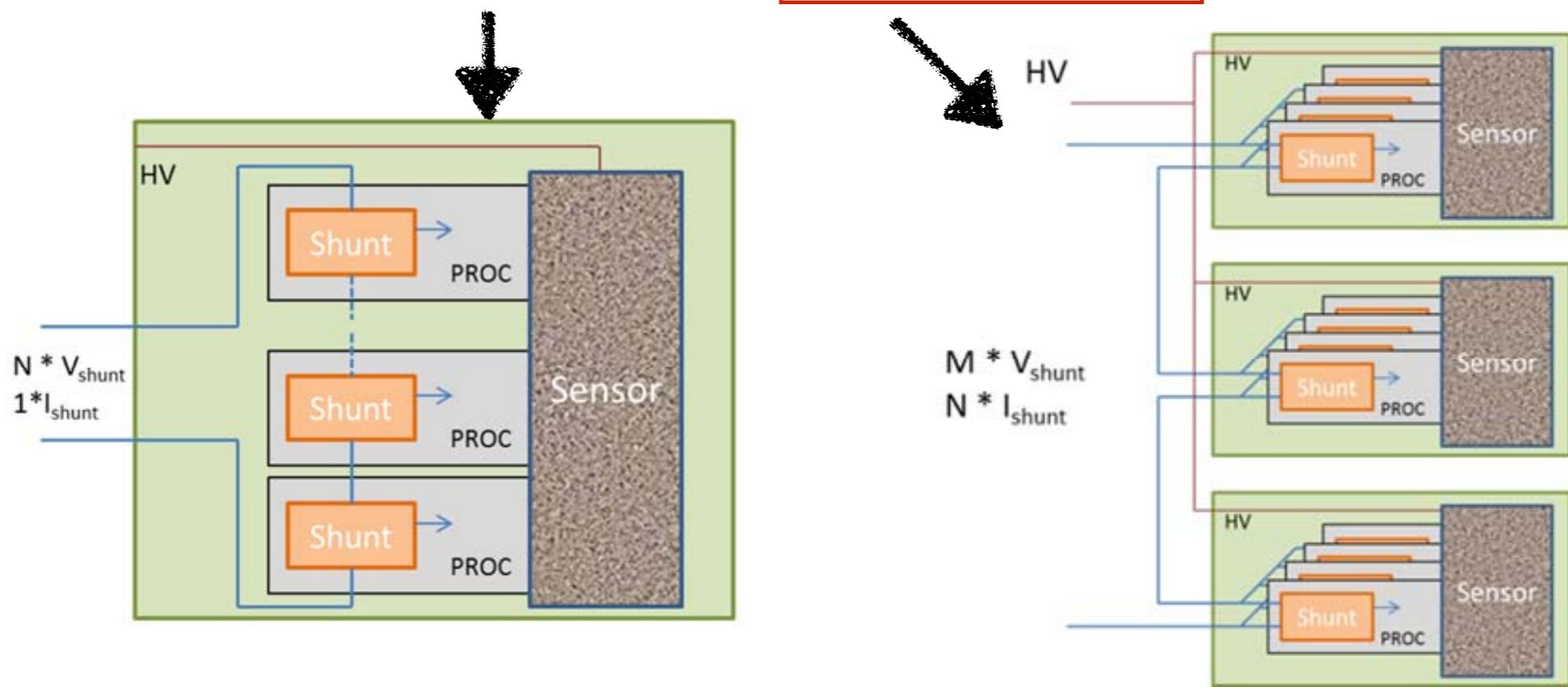
DD: 1.5e15 n/cm<sup>2</sup>

SEEs : no destructive event to LET < 40 MeVcm<sup>2</sup>mg<sup>-1</sup>

No reset, negligible SETs in hadron environments

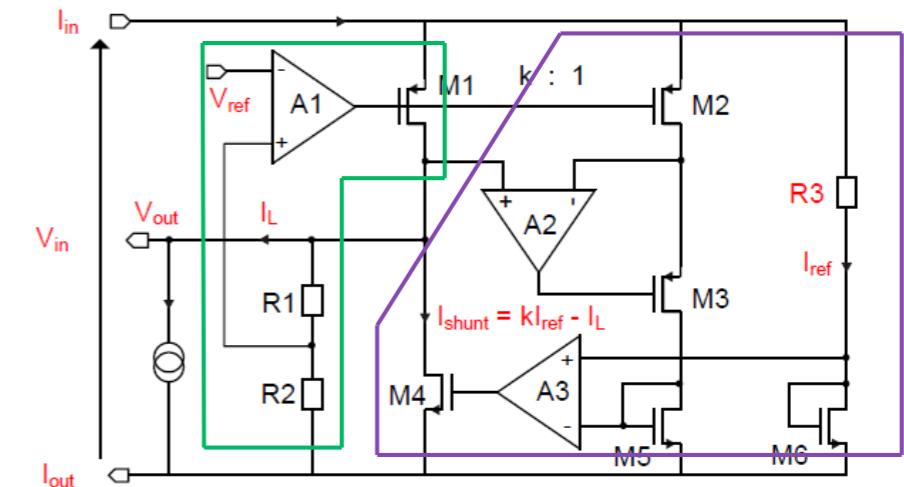
# Inner Tracker: Serial Powering

- Serial Powering is the baseline choice for CMS to power the px phase2 detector
- space, rad. levels → on-module DC-DC conversion currently excluded
- Two options: in-module, **across-module** serial powering



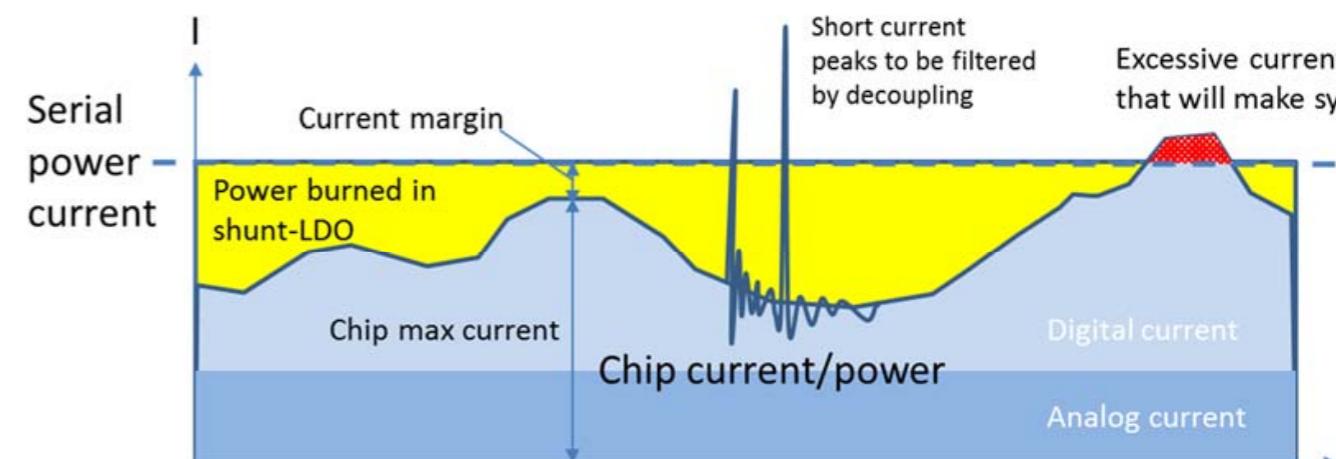
# collaborazione tra ATLAS e CMS

- ATLAS ha già fatto esperienza col serial power nel corso del progetto IBL
- FEI3, FEI4 sono dotati di circuito “shunt-LDO” e possono essere configurati per S.P.
- in corso studi su SP utilizzando FEI4
  - sistemi USBPIX3
- prossimi tests su 65nm ShuntLDO testchip irraggiati
- r/o chip fase2 → RD53

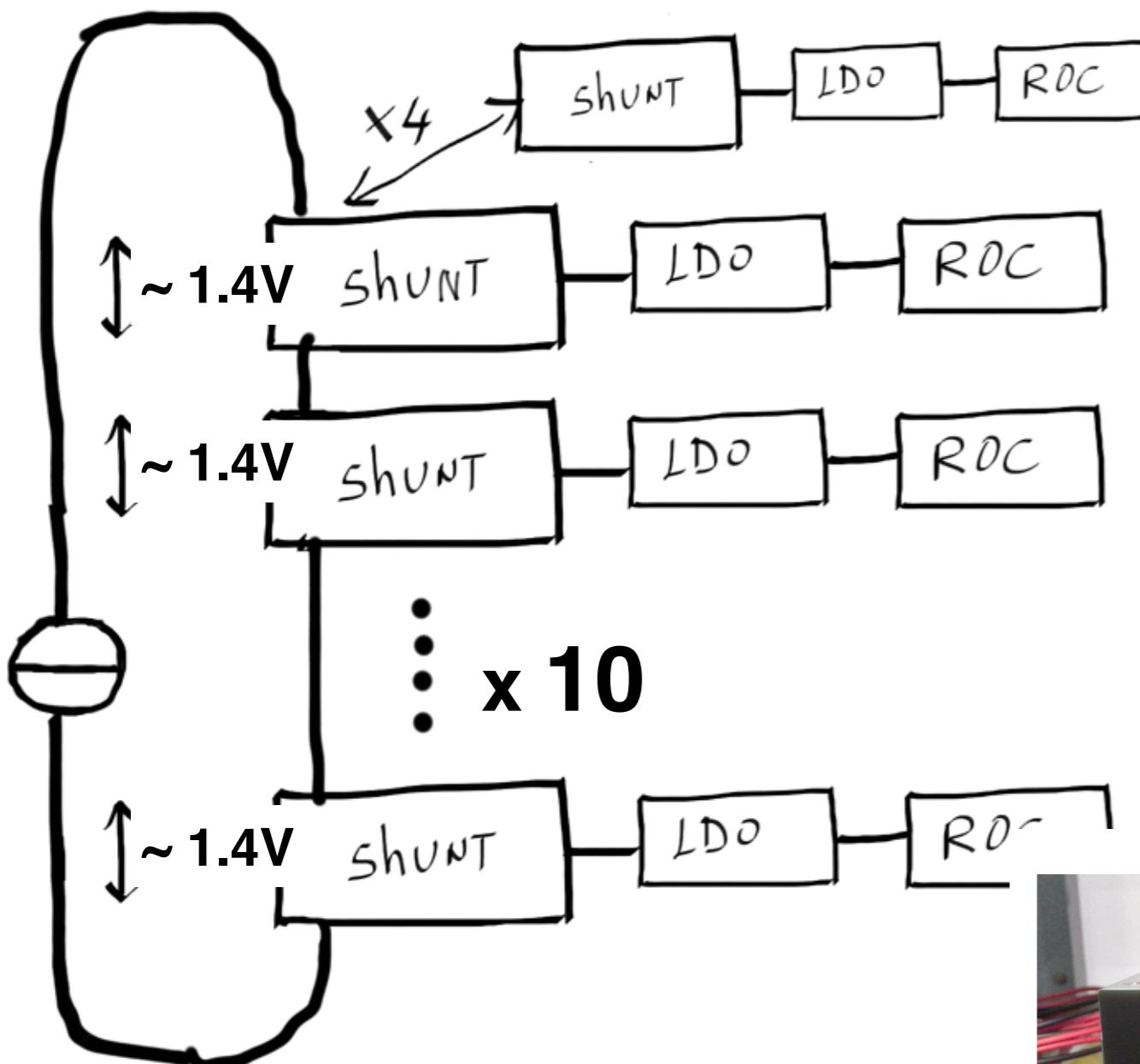


## Distribuzione di HV in parallelo

**Studio di transienti, power-ON/OFF e variazione dei consumi**



# Possibile proiezione sul back-end



**I ~ 10A**  
**V ~ 10-20 V**  
**~ 500 power loops**



- AC/DC + 2-stage DC/DC
- Current and voltage regulated  
→ I and V comparators controlling the final PWM circuitry)
- Imax 2.3 A
- Vmax 10.5 V